CLAIMS

What we claim is:

1. A method for the manufacture of copper microalloys characterized by starting from a copper alloy containing impurities such as S, Se, As, Sb, Bi, Sn, Zn, Ni, Fe, Ag and Te in amounts of the order of tens of weight ppm, comprising the addition of lead to a final concentration of 200 weight ppm or higher in the solid microalloy or of refining the copper microalloy to said concentration.

2. The method according to claim 1, applied to batch casting, semi-continuous casting or continuous casting.

3. The method according to claims 1 ~~and 2,~~ characterized by optionally comprising a pre-heating treatment at 550-650°C for 5-600 s that decreases the softening temperature, the annealing temperature and the recrystallization temperature to values of 200°C or lower, of copper microalloys with less than 80 weight ppm of the impurities Zn, Ag, Cd, Sb, Ni, Fe, Bi, Sn and S, produced by the casting method described in claims 1 ~~and 2.~~

4. A pre-heating treatment at 550-650°C for 5-600 s that, applied to the copper microalloy with contents lower than 80 weight ppm of the impurities Zn, Ag, Cd, Sb, Ni, Fe, Bi, Sn and S, produced by the casting method described in claims 1 ~~and 2,~~ increases the electrical conductivity to the values of the tough-pitch copper, which means 101%IACS or more.

Add Bi

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